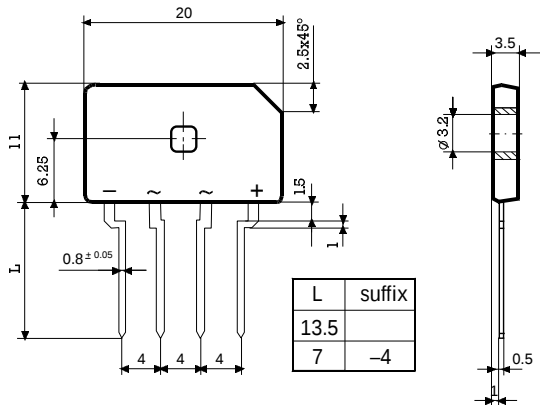




FBI2A4S1.....FBI2M4S1

2 Amp. Glass Passivated Bridge Rectifier

Dimensions in mm.  Plastic Case <table border="1" data-bbox="480 763 603 857"> <tr> <th>L</th> <th>suffix</th> </tr> <tr> <td>13.5</td> <td></td> </tr> <tr> <td>7</td> <td>-4</td> </tr> </table> • Mounting Instructions • High temperature soldering guaranteed: 260 °C – 10 sc. • Recommended mounting torque: 8 Kg.cm.	L	suffix	13.5		7	-4	Voltage 50 to 1000 V. Current 2 A.  • Glass Passivated Junction Chips. • UL recognized under component index file number E130180. • Lead and polarity identifications. • Case: Molded Plastic. • Ideal for printed circuit board (P.C.B.). • The plastic material carries U/L recognition 94 V-O.
L	suffix						
13.5							
7	-4						

Maximum Ratings, according to IEC publication No. 134

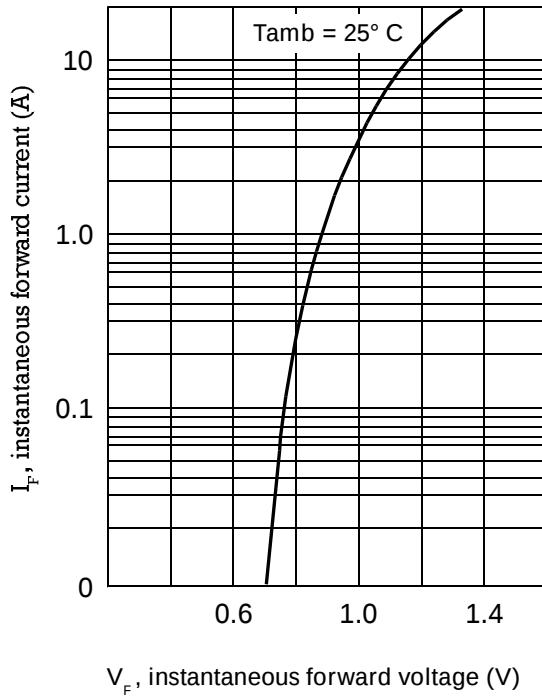
		FBI2A 4S1	FBI2B 4S1	FBI2D 4S1	FBI2G 4S1	FBI2J 4S1	FBI2K 4S1	FBI2M 4S1
V_{RRM}	Peak recurrent reverse voltage (V)	50	100	200	400	600	800	1000
V_{RMS}	Maximum RMS voltage (V)	35	70	140	280	420	560	700
$I_{F(AV)}$	Max. Average forward current with heatsink without heatsink	4.5 A at 65 °C 2.0 A at 25 °C						
I_{FSM}	8.3 ms. peak forward surge current (Jedec Method)	60 A						
I^2t	Rating for fusing ($t < 8.3$ ms.)	15 A ² sec						
V_{DIS}	Dielectric strength (terminals to case, AC 1 min.)	1500 V						
T_j	Operating temperature range	– 55 to + 150 °C						
T_{stg}	Storage temperature range	– 55 to +150 °C						

Electrical Characteristics at Tamb = 25°C

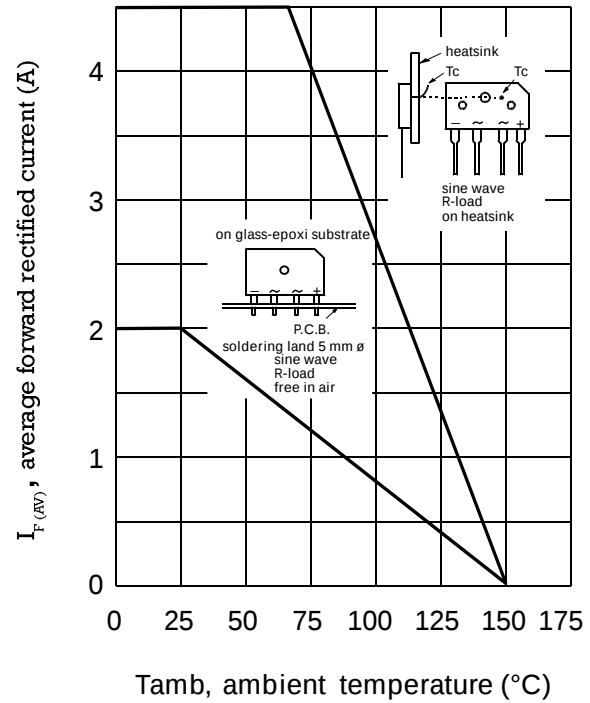
V_F	Max. forward voltage drop per element at $I_F = 2$ A	1.0 V
I_R	Max. reverse current per element at V_{RRM}	5 μ A
$R_{th(j-c)}$	MAXIMUM THERMAL RESISTANCE Junction-Case. With Heatsink.	12 °C/W
$R_{th(j-a)}$	Junction-Ambient. Without Heatsink.	40 °C/W

Characteristic Curves

TYPICAL FORWARD CHARACTERISTIC



FORWARD CURRENT DERATING CURVE



MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

